

V11

Packaged PIN Diodes

Features

- High Power
- Fast Speed
- Voltage Ratings to 1500 Volts
- Wide Selection of Carrier Lifetimes
- Wide Selection of Capacitances
- Assortment of Packages Styles
- Available Screened for Military Applications
- RoHS Compliant

Description and Applications

M/A-COM Tech's broad line of packaged PIN diodes encompass a comprehensive range of electrical characteristics and package outlines. This diverse union of semiconductor technology and chip packaging gives considerable flexibility to the circuit designer. The fast switching series of Packaged PIN Diodes utilize a thin I-region, silicon oxide or glass passivated chip which provides for low leakage current and low insertion loss. With the use of in process control monitors to regulate wafer fabrication parameters, these devices will achieve consistent performance in control circuit applications. The high voltage product line of Packaged PIN Diodes employs M/A-COM Tech's CERMACHIP® passivation process which provides for a hard glass encapsulation that hermetically seals and protects the active area of the chip. These packaged CERMACHIP® PIN diodes are ideally suited for use in high power applications where high level RF voltages are present. The diode chips are bonded into sealed ceramic packages that are designed for the most stringent electrical and environmental conditions. An extensive choice of package styles are available which may be used in a wide variety of RF microwave circuits. The Packaged PIN Diodes series are designed to have a high inherent reliability and may be ordered screened to meet many MIL-STD requirements.

Parameter	Absolution Max.
Voltage	As Specified in Table
Operating Temperature	- 65°C to +175°C
Storage Temperature	- 65°C to +200°C
Operating and Storage (Case Style 1088)	- 65°C to +125°C

1. Operation beyond any one of the above conditions may cause permanent damage to the device.

Specifications subject to change without prior notification.

1

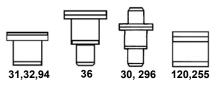
ADVANCED: Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed. PRELIMINARY: Data Sheets contain information regarding a product M/A-COM Technology

Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

Maximum Power Dissipation

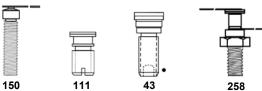
<u>Cathode Heatsink Packages</u> 30,31,32,36,43,94,111,120, 150,255 258,296,1072,1079	P _{diss} = <u>T (max_oper.) - 25°C</u> Thermal Resistance
Leaded Packages +25°C	D 070 W
144, 186, 276,1088	P _{diss} = 250mW
Surface Mount Package +25°C	
1056	P _{diss} = 300mW

Co-Axial Packages



Leaded/Surface Mount Packages

Threaded Packages



Unpackaged Die



131,132.134 , 212

- North America Tel: 800.366.2266 Europe Tel: +353.21.244.6400
- India Tel: +91.80.43537383
 China Tel: +86.21.2407.1588
- Visit www.macomtech.com for additional data sheets and product information.

M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.



Packaged PIN Diodes

V11

100V to 250V Fast Switching PIN Diodes Specifications (T_{AMB} = +25°C)

	Minimum	(Unless otherwise specified)	(Unless otherwise specified)	Maximum	Nomina	I Charac	cteristics
Part Number	Reverse Voltage ¹	Maximum Capacitance	Maximum Series Res.	Thermal Resistance	Corrier		I-Region Width
	@ I _R <10µA	С _т @ -10V f = 1MHz	R _s @ 10mA f = 500MHz		Carrier Lifetime⁴	T _{RR} ⁵	Microns
	Volts	pF	Ω	°C/W	nS	nS	μM
MA4P202-120	100	0.25	2.50	60	60	5	12
MA4P203-30	100	0.35	1.50	30	100	20	12
MA4P303-32	200	0.35	1.50	30	200	60	20
MA4P404-30	250	0.40 ²	0.70 ³	20	1000	100	30

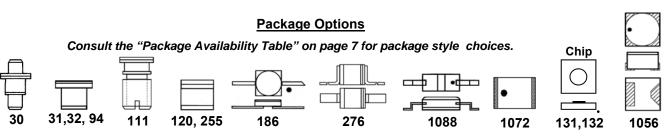
Notes:

1. The minimum specified V_R (Reverse Voltage) is sourced and the resultant reverse leakage current, Ir, is measured to be <10µA

2. At $V_R = -50V$

3. R_s measured at I_F = +50mA, f = 100MHz.

4. Nominal carrier life time specified with diode biased at I_F = +10mA , I_{REV} = -6mA



Package Dimensions can be found on the M/A-COM Technology Solutions website

35V to 500V MELF General Purpose Switching Diodes Specifications (T_{AMB} = +25°C)

	Minimum Reverse	Maximum	(Unless otherwise specified) Maximum	CW Power Dissipation	Nomi	nal Character	istics
Part Number ¹	Voltage ²	Capacitance	Series Res.	Rating	T	Carrier	I-Region
	I _R <10µA Volts	C⊤@10V f = 1MHz pF	R _s @10mA f = 100MHz Ω	Watts	Typical I _F When R _s = 75Ω mA	Lifetime ³	Width
MA4PH235-1072T	35	1.2	0.50	1.0	_	0.3	0.4
MADP-000593-10720T	150	1.5	0.55	10	_	1.0	21
MA4PH236-1072T	600	0.5	3.0	1.0		1.5	2.0
MA4PH237-1079T	200	1.5	0.6@50mA	2.0		3.0	3.0
MA4PH238-1072T	200	0.5	6.0	1.0	0.30-0.60	2.0	4.0
MA4PH239-1079T	200	0.8	25.0	2.0	1.20-2.40	6.0	14.0
MADP-000234-10720T	500	1.5 ⁴	0.25@100mA	5.0		3.0	2.0

Notes:

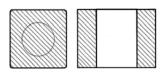
2

1. Only available in case styles indicated.

- The minimum specified V_R (Reverse Voltage) is sourced and the resultant reverse leakage current, Ir, is measured to be <10μA.
- 3. Nominal carrier life time specified with diode biased at I_F = +10mA , I_{REV} = -6mA
- 4. Ct tested at 100V

ADVANCED: Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed. PRELIMINARY: Data Sheets contain information regarding a product M/A-COM Technology

Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.



Case Styles 1072, 1079

- North America Tel: 800.366.2266 Europe Tel: +353.21.244.6400
- India Tel: +91.80.43537383 China Tel: +86.21.2407.1588
- Visit www.macomtech.com for additional data sheets and product information.

M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.



V11

Packaged PIN Diodes

	500V PIN Diddes Specifications (TAMB - +25 C)					
Part Number	Minimum Reverse Voltage ¹	Maximum Capacitance	Maximum Series Resistance	CW Power Dissipation Rating	Nominal Cha	aracteristics
Part Number	I _R <10μΑ Volts	C⊤@100V f = 1 MHz pF	R _s @100mA f = 100 MHz Ω	Watts	Carrier Lifetime ² μS	I-Region Width mils
MA4P504-30	500	0.40	0.60	10	1.0	2
MADP000015-000030 ³	500	0.55	0.45	15	2.0	2
MA4P506-30	500	0.90	0.30	15	3.0	2

500V PIN Diodes Specifications (Two = +25°C)

Notes:

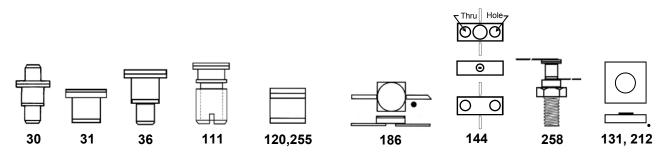
1. The minimum specified V_R (Reverse Voltage) is sourced and the resultant reverse leakage current, Ir, is measured to be <10µA.

2. Nominal carrier life time specified with diode biased at I_{F} = +10mA , I_{REV} = -6mA

3. To order this part in a package style other than 30, use the prefix MA4P505 followed by a dash and the desired package style.

Package Options

Consult the "Package Availability Table" on page 7 for package style choices.



Package dimensions can be found on the M/A-COM Technology Solutions website.

500V MELF PIN Diode Specifications (T_{AMB} = +25°C)

	Minimum Reverse Voltage ¹	Maximum Capacitance	Maximum Series Resistance	CW Power Dissipation Rating	Nominal Cha	aracteristics
Part Number	I _R <10µA Volts	С _т @100V f = 1 MHz pF	R _s @100mA f = 100 MHz Ω	Watts	Carrier Lifetime ² μS	I-Region Width mils
MA4P504-1072T	500	0.5	0.60	10	1.0	2
MA4P505-1072T	500	0.65	0.45	15	2.0	2
MA4P506-1072T	500	1.0	0.30	15	3.0	2

Notes:

1. The minimum specified $V_{\text{R}} \, (\text{Reverse Voltage})$ is sourced and the resultant reverse leakage current, Ir, is measured to be <10µA.

2. Nominal carrier life time specified with diode biased at $I_F = +10mA$, $I_{REV} = -6mA$

3 Specifications subject to change without prior notification.

ADVANCED: Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed. **PRELIMINARY:** Data Sheets contain information regarding a product M/A-COM Technology

Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

1072 Package



• North America Tel: 800.366.2266 • Europe Tel: +353.21.244.6400 • India Tel: +91.80.43537383 • China Tel: +86.21.2407.1588

Visit www.macomtech.com for additional data sheets and product information.

M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.



V11

Packaged PIN Diodes

1	1000V CERMACHIP PIN Diodes Specification (T _{AMB} = +25°C)					
Part Number	Minimum Reverse Voltage ¹	Maximum Capacitance	Maximum Series Resistance	CW Power Dissipation Rating	Nominal Ch	aracteristics
Fart Number	I _R <10µA Volts	С _т @100V f = 1MHz pF	R _s @100mA f = 100MHz Ω	Watts	Carrier Lifetime ² μS	I-Region Width Mils
MA4P604-30	1000	0.50	1.00	15	3.0	4
MA4P606-30	1000	0.80	0.70	20	4.0	4
MA4P607-43	1000	2.00	0.40	25	5.0	4

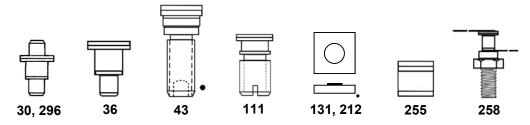
Notes:

1. The maximum specified V_R (reverse voltage) is sourced and the resultant reverse leakage current, Ir, is measured to be <10 μ A

2. Nominal carrier life time specified with diode biased at I_F = +10mA , I_{REV} = -6mA

Package Options

Consult the "Package Availability Table" on page 7 for package style choices.



Package dimensions can be found on the M/A-COM Technology Solutions website.

1500V CERMACHIP PIN Diode Specifications (T_{AMB} = +25°C)

	Minimum Reverse Voltage ¹	Maximum Capacitance	Maximum Series Resistance	Maximum Thermal Resistance	Nominal Cha	
Part Number	I _R <10µA Volts	Ct @100V f = 1MHz pF	R _s @200mA f = 100MHz Ω	°C/W	Carrier Lifetime² μS	I-Region Width mils
MA4P709-150	1500	3.30	0.25	2	10.0	7

Notes:

4

1. The minimum specified V_R (reverse voltage) is sourced and the resultant reverse leakage current, Ir, is measured to be ${<}10\mu A$

2. Nominal carrier life time specified with diode biased at I_F = +10mA , I_{REV} = -6mA



Specifications subject to change without prior notification.

ADVANCED: Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed. PRELIMINARY: Data Sheets contain information regarding a product M/A-COM Technology

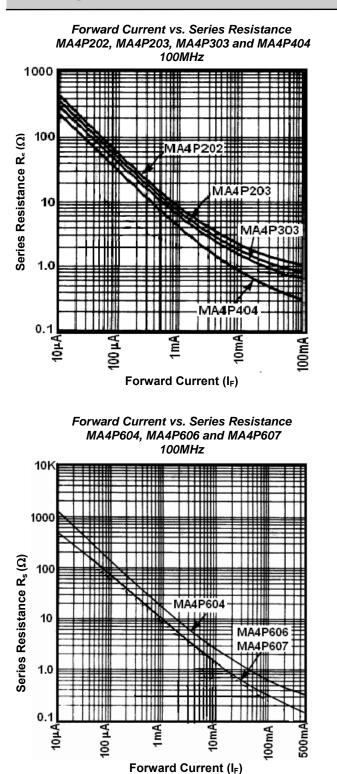
- North America Tel: 800.366.2266
 Europe Tel: +353.21.244.6400
 India Tel: +91.80.43537383
 China Tel: +86.21.2407.1588
- Visit www.macomtech.com for additional data sheets and product information.

PRELIMINARY: Data Sheets contain information regarding a product MIA-COM Technology Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

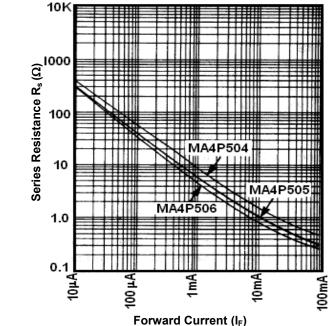
M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.



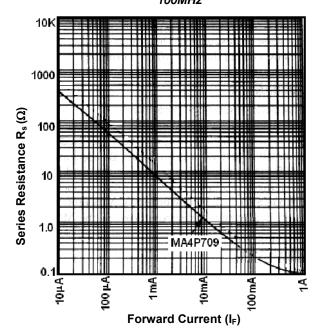
Packaged PIN Diodes



Forward Current vs. Series Resistance MA4P504, MA4P505 and MA4P506 100MHz



Forward Current vs. Series Resistance MA4P709 100MHz



ADVANCED: Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed. PRELIMINARY: Data Sheets contain information regarding a product M/A-COM Technology North America Tel: 800.366.2266
 Europe Tel: +353.21.244.6400
 India Tel: +91.80.43537383
 Visit www.macomtech.com for additional data sheets and product information.

Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

V11



Recommended Groups B & C Testing Per MIL-STD 750

Recommended methods and conditions for Groups B, C and equivalent TX and TXV level screening.

Inspection	Method	Condition
Storage Temperature	1031	See Maximum Ratings
Operating Temperature		See Maximum Ratings
Temperature Cycling	1051	5 cycles - 65°C to +150°C
Shock	2016	500g's
Vibration	2056	15g's
Constant Acceleration	2006	20,000g's
Humidity	1021	10 Days

Recommended Screening Per MIL-STD 750

Recommended methods and conditions for equivalent TX and TXV level screening.

Inspection	Method	Condition
Internal Visual and / or X-Ray	2072, 2076	See Note
High Temp. Storage	1032	48 hours min. @ max. storage temp.
Thermal Shock	Thermal Shock 1051	
Constant Acceleration	2006	20,000 g's, Y1
Fine Leak	1071	Н
Gross Leak	1071	C or E
Electrical		See Note
Burn-In	1038	See Note

Notes:

1. Conditions and details of test depend on specific model number. Information available upon request.

2. Case styles 1056 and 1088 are not military, MIL-STD-750, rated packages.

- ADVANCED: Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed. PRELIMINARY: Data Sheets contain information regarding a product M/A-COM Technology
- North America Tel: 800.366.2266
 Europe Tel: +353.21.244.6400
 India Tel: +91.80.43537383
 China Tel: +86.21.2407.1588
- Visit www.macomtech.com for additional data sheets and product information.

PRELIMINARY: Data Sheets contain information regarding a product MIA-COM Technology Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.



Packaged PIN Diodes

V11

Maximum Soldering Temperature

For hand soldering operation:

Case Style: 120, 144, 150*,186, 255, 258*, 276, 1088, 1072, 1079 ◆ 265°C maximum for 5 seconds Case Style: 30*, 31, 32, 36*, 43*, 94, 111*, 296* ◆ 225°C maximum for 5 seconds. *Note:

Package styles that are threaded or have pronged ends rely on a pressure connection and do not require solder attachment but can be soldered if desired.

For solder reflow profiles:

Refer to application note M-538 on the M/A-COM website using the following link: http://www.macomtech.com/Application%20Notes/pdf/M538.pdf

Ordering Information

The Packaged PIN Diode specifications shown in the tables on pages 2, 3, & 4 are for the standard style package. The standard package style is indicated by the number following the dash after the base part number. Note that the specification tables lists the total diode capacitance for the standard case style. The total capacitance for the base part in an alternative package will differ and is computed by adding the junction capacitance of the chip and the parasitic capacitance of the alternative package as defined in the **Package Parasitic Capacitance** table below. To compute the chip junction capacitance, subtract the total capacitance shown in the specifications tables on pages 2, 3, & 4 from the appropriate standard style package capacitance below. To order, indicate the base part number followed by a dash and the desired package style.

For example: The MA4P506-258 is the MA4P506 chip in the 258 style package.

Tuokuge Avanability Table					
Base Part Number	Available ODS Package Styles				
MA4P202	120, 134, 276, 1056				
MA4P203	30, 32, 94, 111, 134, 1056				
MA4P303	32, 36, 94, 120, 186, 255, 1088				
MA4P404	30, 31, 36, 111, 132, 258,1072T*				
MA4P504	30, 120, 132, 144, 186, 255,1072T*				
MA4P505	36, 131, 255, 1072T*				
MA4P506	30, 31, 36, 131, 255, 258, 1072T*				
MA4P604	30, 43, 131, 255, 258				
MA4P606	30, 36, 131, 258				
MA4P607	43, 212, 296				
MA4P709	150				
MADP000015-000030	30				
MA4PH235	1072T*				
MA4PH236	1072T*				
MA4PH237	1079T*				
MA4PH238	1072T*				
MA4PH239	1079T*				
MADP-000234	10720T* (1072 package style)				

Package Availability Table

Package Style	Cap. (pF)
30	0.18
31	0.18
32	0.30
36	0.18
43	0.75
94	0.15
111	0.27
120	0.13
131	N/A (chip)
132	N/A (chip)
134	N/A (chip)
144	0.42
186	0.15
212	N/A (chip)
255	0.30
258	0.18
276	0.13
296	0.35
1056	0.20
1072	0.16
1079	0.13
1088	0.12

*Note: "T" after the package style number indicates tape and reel.

Tape and reel information can be found on the M/A-COM website at http://www.macomtech.com/Application%20Notes/pdf/M513.pdf Package dimensions can be found on the M/A-COM website at http://www.macomtech.com/Application%20Notes/pdf/M513.pdf Package dimensions can be found on the M/A-COM website at http://www.macomtech.com/Application%20Notes/pdf/M513.pdf

ADVANCED: Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed. PRELIMINARY: Data Sheets contain information regarding a product M/A-COM Technology

7

North America Tel: 800.366.2266
 Europe Tel: +353.21.244.6400
 India Tel: +91.80.43537383
 China Tel: +86.21.2407.1588

Visit www.macomtech.com for additional data sheets and product information.

Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

Package Parasitic Capacitance